



Electronic Filing System (EFS) Data
Electronic Patent Application Submission
USPTO Use Only

2826
RECEIVED
AUG 15 2003
TECHNOLOGY CENTER 2800

EFS ID: 45429
Application ID: 10054124
Title of Invention: SEMICONDUCTOR PACKAGE
INCLUDING LEADS WITH
VERTICALLY DOWNSET INNER
ENDS
First Named Inventor: JEFFREY MIKS
Domestic/Foreign Application: Domestic Application
Filing Date: 2003-08-12
Effective Receipt Date: 2003-08-12
Submission Type: Information Disclosure
Statement
Filing Type:
Confirmation number: 6418
Attorney Docket Number: AMKOR003A
Total Fees Authorized: 180.0
Payment Category: Deposit Account
Deposit Account Number: 502304
Deposit Account Name: Mark B. Garred
Access Code: *****
RAM Payment Status: RAM success
RAM User ID: EFSPROD
RAM Accounting Date: 2003-08-12
RAM Sequence Number: 7




Digital Certificate Holder: cn=Mark B. Garred,ou=Registered Attorneys,ou=Patent and Trademark
Office,ou=Department of Commerce,o=U.S. Government,c=US
Certificate Message Digest: d6b00e4d816a7db2bbd18ea1db549779c737dc9c



ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v18

Stylesheet Version v18.0

Title of Invention	SEMICONDUCTOR PACKAGE INCLUDING LEADS WITH VERTICALLY DOWNSET INNER ENDS																										
<p>Application Number: 10/054124 </p> <p>Confirmation Number: 6418</p> <p>First Named Applicant: JEFFREY MIKS</p> <p>Attorney Docket Number: AMKOR003A</p> <p>Art Unit: 2826</p> <p>Search string: (6258629).pn.</p> <p>US Patent Documents</p> <p>Note: Applicant is not required to submit a paper copy of cited US Patent Documents</p> <table border="1"><thead><tr><th>init</th><th>Cite.No.</th><th>Patent No.</th><th>Date</th><th>Patentee</th><th>Kind</th><th>Class</th><th>Subclass</th></tr></thead><tbody><tr><td></td><td>1</td><td>6258629</td><td>2001-07-10</td><td>EULOGIA A. NIONES ET AL</td><td></td><td></td><td></td></tr></tbody></table> <p>Signature</p> <table border="1"><thead><tr><th>Examiner Name</th><th>Date</th></tr></thead><tbody><tr><td></td><td></td></tr></tbody></table>								init	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass		1	6258629	2001-07-10	EULOGIA A. NIONES ET AL				Examiner Name	Date		
init	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass																				
	1	6258629	2001-07-10	EULOGIA A. NIONES ET AL																							
Examiner Name	Date																										


RECEIVED
AUG 15 2003
TECHNOLOGY CENTER 2800



TRANSMITTAL

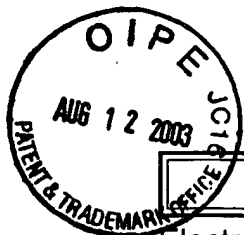
Electronic Version v1.1

Stylesheet Version v1.1.0

Title of Invention	SEMICONDUCTOR PACKAGE INCLUDING LEADS WITH VERTICALLY DOWNSET INNER ENDS															
<div>Application Number: 10/054124 </div> <div>Date: 2003-08-12</div> <div>First Named Applicant: JEFFREY ALAN</div> <div>Confirmation Number: 6418</div> <div>Attorney Docket Number: AMKOR003A</div> <div>RECEIVED AUG 15 2003 TECHNOLOGY CENTER</div>																
<p>I hereby certify that the use of this system is for OFFICIAL correspondence between patent applicants or their representatives and the USPTO. Fraudulent or other use besides the filing of official correspondence by authorized parties is strictly prohibited, and subject to a fine and/or imprisonment under applicable law.</p> <p>I, the undersigned, certify that I have viewed a display of document(s) being electronically submitted to the United States Patent and Trademark Office, using either the USPTO provided style sheet or software, and that this is the document(s) I intend for initiation or further prosecution of a patent application noted in the submission. This document(s) will become part of the official electronic record at the USPTO.</p>																
<table border="1"><thead><tr><th>Submitted by:</th><th>Elec. Sign.</th><th>Sign. Capacity</th></tr></thead><tbody><tr><td>MARK B GARRED Registered Number: 34823</td><td>/mbg/</td><td>Attorney</td></tr></tbody></table>			Submitted by:	Elec. Sign.	Sign. Capacity	MARK B GARRED Registered Number: 34823	/mbg/	Attorney								
Submitted by:	Elec. Sign.	Sign. Capacity														
MARK B GARRED Registered Number: 34823	/mbg/	Attorney														
<table><tr><td>Documents being submitted</td><td>Files</td></tr><tr><td>us-ids</td><td>ids-usidst.xml</td></tr><tr><td></td><td>us-ids.dtd</td></tr><tr><td></td><td>us-ids.xsl</td></tr><tr><td>us-fee-sheet</td><td>ids-usfees.xml</td></tr><tr><td></td><td>us-fee-sheet.xsl</td></tr><tr><td></td><td>us-fee-sheet.dtd</td></tr></table>			Documents being submitted	Files	us-ids	ids-usidst.xml		us-ids.dtd		us-ids.xsl	us-fee-sheet	ids-usfees.xml		us-fee-sheet.xsl		us-fee-sheet.dtd
Documents being submitted	Files															
us-ids	ids-usidst.xml															
	us-ids.dtd															
	us-ids.xsl															
us-fee-sheet	ids-usfees.xml															
	us-fee-sheet.xsl															
	us-fee-sheet.dtd															



Comments

**FEE TRANSMITTAL**

Electronic Version v08
Stylesheet Version v08.0

Title of Invention	SEMICONDUCTOR PACKAGE INCLUDING LEADS WITH VERTICALLY DOWNSET INNER ENDS										
<p>Application Number: 10/054124 </p> <p>Date: 2003-08-12</p> <p>First Named Applicant: JEFFREY ALAN MIKS</p> <p>Attorney Docket Number: AMKOR003A</p> <p>Art Unit: 2826</p>											
<p>TOTAL FEE AUTHORIZED \$180</p> <p>Patent fees are subject to annual revisions on or about October 1st of each year.</p>											
BASIC FILING FEE											
<table border="1"><thead><tr><th>Fee Description</th><th>Fee Code</th><th>Amount \$</th><th>Fee Paid \$</th></tr></thead><tbody><tr><td>Submission Of Information Disclosure Stmt Fee</td><td>1806</td><td>180</td><td>180</td></tr></tbody></table>				Fee Description	Fee Code	Amount \$	Fee Paid \$	Submission Of Information Disclosure Stmt Fee	1806	180	180
Fee Description	Fee Code	Amount \$	Fee Paid \$								
Submission Of Information Disclosure Stmt Fee	1806	180	180								
<p>AUTHORIZED BILLING INFORMATION</p> <p>The commissioner is hereby authorized to charge indicated fees and credit any overpayments to:</p> <p>Deposit account number: 502304</p> <p>Access Code: ****</p> <p>Deposit name: Stetina Brunda Garred Brucker</p> <p>Deposit authorized name: Mark B. Garred</p> <p>Signature: /mbg/</p> <p>Date (YYYYMMDD): 2003-08-12</p>											

RECEIVED
AUG 15 2003
TECHNOLOGY CENTER 2800